

	Type	Hits	Search Text	DBs
1	BRS	1213	semiconductor adj energy adj laboratory	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB
2	BRS	66774	cmos	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB
3	BRS	18350	tft	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB
4	BRS	432	"insulation only"	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB
5	BRS	0	((semiconductor adj energy adj laboratory) and cmos and tft) and "insulation only"	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB
6	BRS	126588	sidewall	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB
7	BRS	5	((semiconductor adj energy adj laboratory) and cmos and tft) and sidewall	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB
8	BRS	273	(semiconductor adj energy adj laboratory) and cmos and tft	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB
9	BRS	1248	cmos and tft	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB
10	BRS	19	sacrificial adj sidewall	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB
11	IS&R	3	("6113702").PN.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB
12	BRS	7649	cmos and wiring	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB
13	BRS	730	cmos and metalization	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB
14	BRS	131	"no sidewall"	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB
15	BRS	672	"no spacer"	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB
16	BRS	5	(cmos and wiring) and "no spacer"	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB
17	BRS	4	(cmos and wiring) and "no sidewall"	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB
18	BRS	7	cmos and tft and "no spacer"	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB
19	IS&R	460	("438/238").CCLS.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB
20	IS&R	596	("438/154").CCLS.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB
21	IS&R	209	("438/199").CCLS.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB
22	BRS	10102	soi	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB
23	BRS	16	((("438/199").CCLS.) and soi	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB
24	IS&R	169	("257/50").CCLS.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB
25	IS&R	187	("257/69").CCLS.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB
26	IS&R	329	("257/204").CCLS.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB
27	IS&R	171	("257/209").CCLS.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB
28	IS&R	1148	("257/347").CCLS.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB
29	IS&R	361	("257/351").CCLS.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB
30	IS&R	462	("257/776").CCLS.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB
31	IS&R	1411	("257/773").CCLS.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB
32	IS&R	956	("257/401").CCLS.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB
33	IS&R	739	("257/390").CCLS.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB
34	IS&R	5	((("5923962") or ("6140667")).PN.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB